PRODUCT / PROCESS CHANGE INFORMATION

| 1. PCI basic data | | |
|--|--|---|
| 1.1 Company STMicroelectronics International N.V | | STMicroelectronics International N.V |
| 1.2 PCI No. | | ADG/17/10225 |
| 1.3 Title of PCI | | PBGA324 (23x23) : Substrate Supplier FAB Transfer and Process Integration (UNIMICRON) |
| 1.4 Product Category | | see list |
| 1.5 Issue date | | 2017-05-09 |

| 2. PCI Team | | |
|---------------------------|---------------------------|--|
| 2.1 Contact supplier | | |
| 2.1.1 Name | ROBERTSON HEATHER | |
| 2.1.2 Phone | +1 8475853058 | |
| 2.1.3 Email | heather.robertson@st.com | |
| 2.2 Change responsibility | | |
| 2.2.1 Product Manager | Luca RODESCHINI | |
| 2.1.2 Marketing Manager | Daniele Alfredo BRAMBILLA | |
| 2.1.3 Quality Manager | Alberto MERVIC | |

| 3. Change | | | |
|---|--------------------|---------------------------------------|--|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location | |
| Transfer of a full process or process brick (process step, control plan, recipes) from one site to another site | (Not Defined) | UNIMICRON (Substrate supplier Taiwan) | |

| 4. Description of change | | | |
|---|---|------------------------------------|--|
| Old New | | New | |
| 4.1 Description | H1-JY FAB (Front End and Back End) and H1-HF FAB (Front End) | H1-HF FAB (Front End and Back End) | |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No impact | | |

| 5. Reason / motivation for change | | |
|-----------------------------------|---|--|
| 5.1 Motivation | Renting lease for substrate supplier of H1_JY FAB will expire on Dec. 31-2016 | |
| 5.2 Customer Benefit | SERVICE CONTINUITY | |

| 6. Marking of parts / traceability of change | |
|--|----------|
| 6.1 Description | Datacode |

| 7. Timing / schedule | | |
|-------------------------------------|--------------|--|
| 7.1 Date of qualification results | 2017-04-30 | |
| 7.2 Intended start of delivery | 2017-06-01 | |
| 7.3 Qualification sample available? | Upon Request | |

| 8. Qualification / Validation | | | |
|---|--------------------------|---------------|------------|
| 8.1 Description | 10225 5W_and_Details.pdf | | |
| 8.2 Qualification report and qualification results | | Issue Date | 2017-05-09 |

9. Attachments (additional documentations)

10225 Public product.pdf 10225 5W_and_Details.pdf

| 10. Affected parts | | |
|---|-----------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No 10.1.2 Supplier Part No | | 10.1.2 Supplier Part No |
| | SPC564A80B4CFAR | |



Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title : PBGA324 (23x23) : Substrate Supplier FAB Transfer and Process Integration (UNIMICRON) *PCI Reference :* ADG/17/10225

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

| SPC564A80B4CFAY | SPC564A70B4COBR | SPC564A70B4COBY |
|-----------------|-----------------|-----------------|
| SPC564A74B4CFAY | SPC564A80B4CFAR | SPC564A80B4COBY |
| SPC564A80B4CFBY | SPC564A70B4CFAY | SPC564A80B4COBR |
| SPC564A70B4CFAR | | |

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